

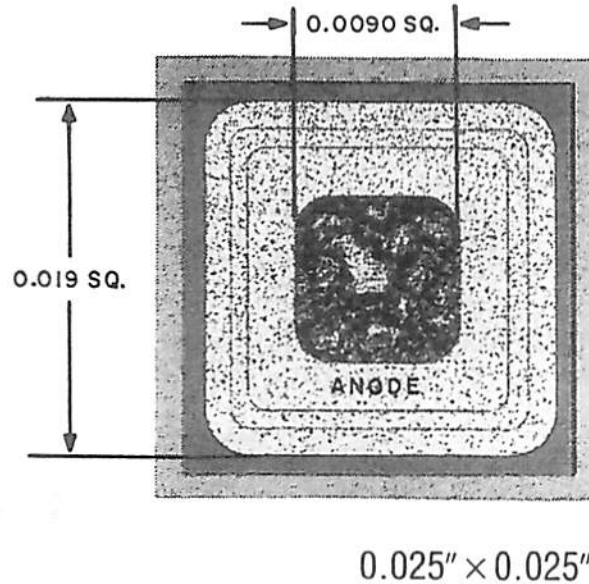


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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



DO NOT BOND TO CENTER AREA

Top Material: Al
 Backside Material: Au
 Bond Pad Size: .009 X .009" See above
 Backside Potential: Cathode
 Mask Ref: ZAA

APPROVED BY: SL

DIE SIZE .025" X .025"

DATE: 5/18/23

MFG: SILICON SUPPLIES

THICKNESS

P/N: TBA 1.8Vz